Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.068”**

**CATHODE**

**ANODE**

**ANODE**

**.041 X .041”**

**.068”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .041 X .041”**

**Backside Potential: CATHODE**

**Mask Ref: RA**

**APPROVED BY: DK DIE SIZE .068” X .068” DATE: 11/16/21**

**MFG: MICROSEMI / PPC THICKNESS .010” P/N: 1N5811**

**DG 10.1.2**

#### Rev B, 7/1